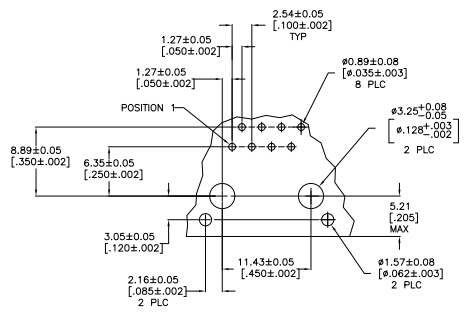
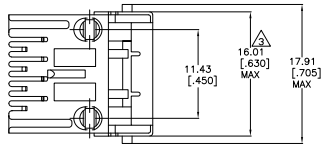
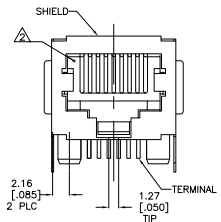
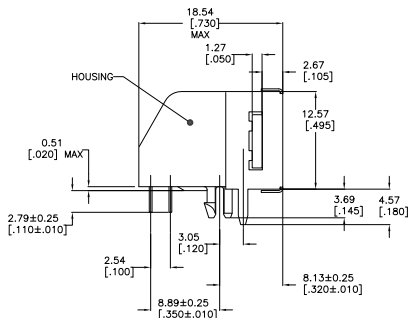
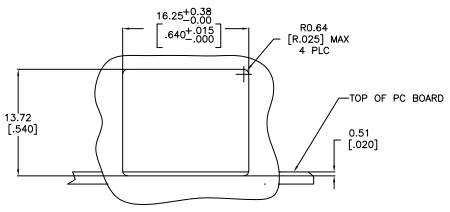


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REV	DATE	DESCRIPTION	BY	CHK	APP
AA	00				
B		E20-07-026027			12/04/07 LAM PR



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)



RECOMMENDED PANEL CUTOUT

- MATERIAL:
 HOUSING - HTN NYLON, COLOR: BLACK
 TERMINAL - 0.36[014] THICK PHOS-BRONZE PLATED WITH 1.27μm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] THICK MINIMUM NICKEL UNDERPLATE.
 SHIELD - 0.25[.010] THICK COPPER ALLOY PLATED WITH 3.0μm[.000120] MINIMUM REFLOWED TIN
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F
- DIMENSION MEASURED ALONG FRONT EDGES OF MATING FACE
- BULK PACKAGED IN A TRAY

5406429-1
 PART NO.

THIS DRAWING IS A CONTROLLED DOCUMENT.		ALCOBETA - 02005	02/02/07	TYS Electronics Corporation Harrisburg, Pa 17105-3608
DESIGNER	REVISIONS	DATE	BY	APP
108-1163	108-1163	114-2048		
SEE NOTE 1	SEE NOTE 1	A1	00779	5406429
CUSTOMER DRAWING		DATE	REV	BY
		4-1	1	B